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March 22, 2002

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TECHNOLOGY CENTER 2800

To: Commissioner of Patents and Trademarks
Washington, D.C. 20231

Fr: George O. Saile, Reg. No. 19,572
20 McIntosh Drive
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 10/061,023 01/30/02

Shyh-Ming Chang et al.

COMPOSITE BUMP BONDING

Grp. Art Unit: 2814

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56. Copies of each document is included herewith.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner of Patents and
Trademarks, Washington, D.C. 20231, on April 1, 2002.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

Sub 4/1/02

U.S. Patent 3,809,625 to Brown et al., "Method of Making Contact Bumps on Flip-Chips," describes a coating of gold on metal bumps.

U.S. Patent 3,401,126 to Miller et al., "Method of Rendering Noble Metal Conductive Composition Non-Wettable by Solder," discusses highly conductive electrodes which are substantially not wetted by solder.

U.S. Patent 4,749,120 to Hatada, "Method of Connecting a Semiconductor Device to a Wiring Board," discusses a method for achieving increased interconnection density.

U.S. Patent 4,963,002 to Tagusa et al., "Connection Construction and Method of Manufacturing the Same," discusses a connection construction which may be advantageously employed for connecting a substrate such as a semiconductor chip to a substrate or the like of a display panel used in various types of display device, and to a method of manufacturing such connection construction.

U.S. Patent 4,916,523 to Sokolovsky et al., "Electrical Connections Via Unidirectional Conductive Elastomer for Pin Carrier Outside Lead Bond," discloses a unidirectional conductive adhesive to bond the integrated circuit chip to the substrate.

ERSO-83-02

U.S. Patent 5,134,460 to Brady et al., "Aluminum Bump, Reworkable Bump, and Titanium Nitride Structure for Tab Bonding," discusses conductive metal bumps coated with a gold layer.

Sincerely,

A handwritten signature in black ink, appearing to read 'SBA', with a long horizontal flourish extending to the right.

Stephen B. Ackerman,
Reg. No. 37761